SN54AC86, SN74AC86
QUADRUPLE 2-INPUT EXCLUSIVE-OR GATES
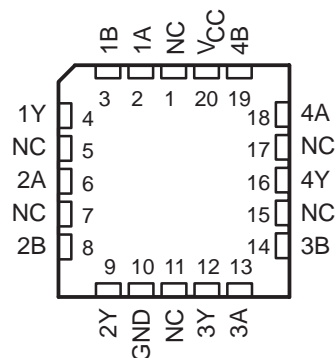
- **2-V to 6-V V$_{CC}$ Operation**
- **Inputs Accept Voltages to 6 V**
- **Max t$_{pd}$ of 9 ns at 5 V**

SN54AC86 . . . J OR W PACKAGE
SN74AC86 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)

1A	1		14	V$_{CC}$
1B	2		13	4B
1Y	3		12	4A
2A	4		11	4Y
2B	5		10	3B
2Y	6		9	3A
GND	7		8	3Y
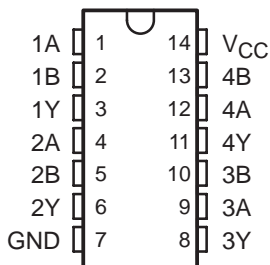
SN54AC86 . . . FK PACKAGE
(TOP VIEW)

Pins (top, left to right): 1B, 1A, NC, V$_{CC}$, 4B
Left side: 1Y (4), NC (5), 2A (6), NC (7), 2B (8)
Right side: 4A (18), NC (17), 4Y (16), NC (15), 3B (14)
Bottom (left to right): 2Y (9), GND (10), NC (11), 3Y (12), 3A (13)
Top numbers: 3, 2, 1, 20, 19

NC – No internal connection

description/ordering information

The 'AC86 devices are quadruple 2-input exclusive-OR gates. The devices perform the Boolean function $Y = A \oplus B$ or $Y = \overline{A}B + A\overline{B}$ in positive logic.

A common application is as a true/complement element. If one of the inputs is low, the other input is reproduced in true form at the output. If one of the inputs is high, the signal on the other input is reproduced inverted at the output.

ORDERING INFORMATION

T$_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74AC86N	SN74AC86N
	SOIC – D	Tube	SN74AC86D	AC86
		Tape and reel	SN74AC86DR	
	SOP – NS	Tape and reel	SN74AC86NSR	AC86
	SSOP – DB	Tape and reel	SN74AC86DBR	AC86
	TSSOP – PW	Tube	SN74AC86PW	AC86
		Tape and reel	SN74AC86PWR	
–55°C to 125°C	CDIP – J	Tube	SNJ54AC86J	SNJ54AC86J
	CFP – W	Tube	SNJ54AC86W	SNJ54AC86W
	LCCC – FK	Tube	SNJ54AC86FK	SNJ54AC86FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TEXAS INSTRUMENTS

FUNCTION TABLE
(each gate)

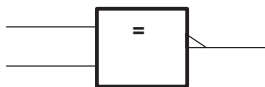| INPUTS		OUTPUT
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L

exclusive-OR logic

An exclusive-OR gate has many applications, some of which can be represented better by alternative logic symbols.
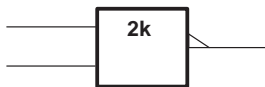
EXCLUSIVE OR
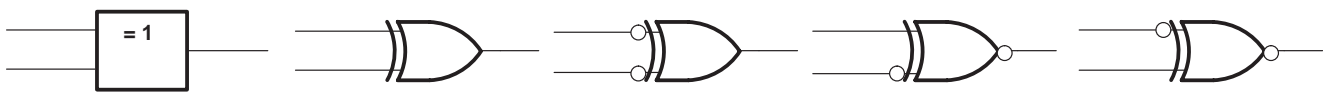
These five equivalent exclusive-OR symbols are valid for an 'AC86 gate in positive logic; negation may be shown at any two ports.
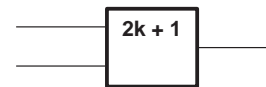
LOGIC-IDENTITY ELEMENT

The output is active (low) if all inputs stand at the same logic level (i.e., A = B).

EVEN-PARITY ELEMENT

The output is active (low) if an even number of inputs (i.e., 0 or 2) are active.

ODD-PARITY ELEMENT

The output is active (high) if an odd number of inputs (i.e., only 1 of the 2) are active.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} .... −0.5 V to 7 V
Input voltage range, V_I (see Note 1) .... −0.5 V to V_{CC} + 0.5 V
Output voltage range, V_O (see Note 1) .... −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) .... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) .... ±20 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) .... ±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package .... 86°C/W
DB package .... 96°C/W
N package .... 80°C/W
NS package .... 76°C/W
PW package .... 113°C/W
Storage temperature range, T_{stg} .... −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

recommended operating conditions (see Note 3)

			SN54AC86 MIN	SN54AC86 MAX	SN74AC86 MIN	SN74AC86 MAX	UNIT
V_{CC}	Supply voltage		2	6	2	6	V
V_{IH}	High-level input voltage	V_{CC} = 3 V	2.1		2.1		V
		V_{CC} = 4.5 V	3.15		3.15		
		V_{CC} = 5.5 V	3.85		3.85		
V_{IL}	Low-level input voltage	V_{CC} = 3 V		0.9		0.9	V
		V_{CC} = 4.5 V		1.35		1.35	
		V_{CC} = 5.5 V		1.65		1.65	
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 3 V		−12		−12	mA
		V_{CC} = 4.5 V		−24		−24	
		V_{CC} = 5.5 V		−24		−24	
I_{OL}	Low-level output current	V_{CC} = 3 V		12		12	mA
		V_{CC} = 4.5 V		24		24	
		V_{CC} = 5.5 V		24		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			8		8	ns/V
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	$T_A = 25°C$ MIN	$T_A = 25°C$ TYP	$T_A = 25°C$ MAX	SN54AC86 MIN	SN54AC86 MAX	SN74AC86 MIN	SN74AC86 MAX	UNIT
V_{OH}	I_{OH} = −50 µA	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I_{OH} = −12 mA	3 V	2.56			2.4		2.46		
	I_{OH} = −24 mA	4.5 V	3.86			3.7		3.76		
		5.5 V	4.86			4.7		4.76		
	I_{OH} = −50 mA[†]	5.5 V				3.85				
	I_{OH} = −75 mA[†]	5.5 V						3.85		
V_{OL}	I_{OL} = 50 µA	3 V		0.002	0.1		0.1		0.1	V
		4.5 V		0.001	0.1		0.1		0.1	
		5.5 V		0.001	0.1		0.1		0.1	
	I_{OL} = 12 mA	3 V			0.36		0.5		0.44	
	I_{OL} = 24 mA	4.5 V			0.36		0.5		0.44	
		5.5 V			0.36		0.5		0.44	
	I_{OL} = 50 mA[†]	5.5 V					1.65			
	I_{OL} = 75 mA[†]	5.5 V							1.65	
I_I	V_I = V_{CC} or GND	5.5 V			±0.1		±1		±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			2		40		20	µA
C_i	V_I = V_{CC} or GND	5 V		2.6						pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

TEXAS INSTRUMENTS

switching characteristics over recommended operating free-air temperature range,
V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC86		SN74AC86		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	2	6.5	11.5	1	14	1.5	12.5	ns
t_{PHL}			2	6	11.5	1	14	1.5	12.5	

switching characteristics over recommended operating free-air temperature range,
V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T_A = 25°C			SN54AC86		SN74AC86		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A or B	Y	1.5	4.5	8.5	1	10	1	9	ns
t_{PHL}			1.5	4.5	8.5	1	10	1	9.5	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 1 MHz	25	pF

PARAMETER MEASUREMENT INFORMATION
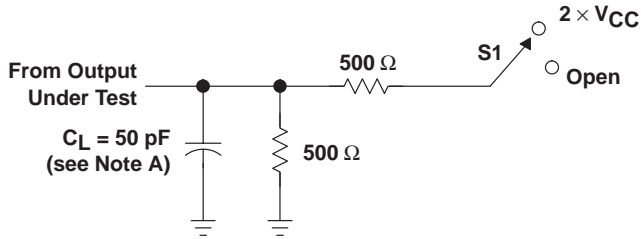
LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
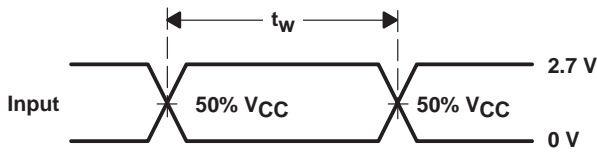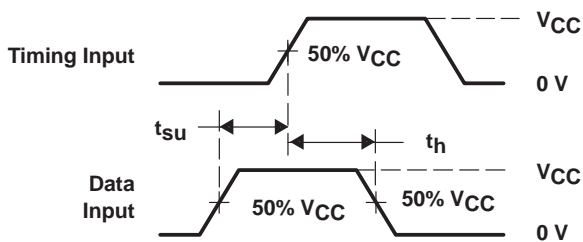
VOLTAGE WAVEFORMS

VOLTAGE WAVEFORMS

VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

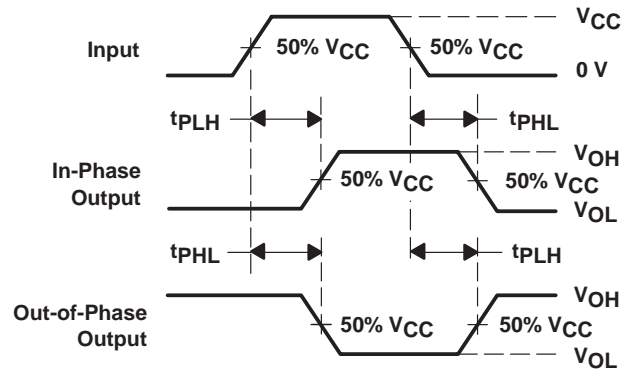| Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
5962-89550012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8955001CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
5962-8955001DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN74AC86D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74AC86DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AC86NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AC86NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86PWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74AC86PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AC86PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54AC86FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AC86J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54AC86W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE MATERIALS INFORMATION

![Texas Instruments logo]

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC86DBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74AC86DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AC86NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AC86PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC86DBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74AC86DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74AC86NSR	SO	NS	14	2000	346.0	346.0	33.0
SN74AC86PWR	TSSOP	PW	14	2000	346.0	346.0	29.0

DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	——	——	——	——
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

C

1   7

$\dfrac{0.065\ (1,65)}{0.045\ (1,14)}$

0.005 (0,13) MIN

$\dfrac{0.060\ (1,52)}{0.015\ (0,38)}$

A

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

$\dfrac{0.026\ (0,66)}{0.014\ (0,36)}$

0.100 (2,54)

0°−15°

$\dfrac{0.014\ (0,36)}{0.008\ (0,20)}$

4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. This package is hermetically sealed with a ceramic lid using glass frit.
         D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
         E. Falls within MIL STD 1835 GDIP1−T14, GDIP1−T16, GDIP1−T18 and GDIP1−T20.

W (R–GDFP–F14)   CERAMIC DUAL FLATPACK

Base and Seating Plane

0.045 (1,14)
0.026 (0,66)

0.260 (6,60)
0.235 (5,97)

0.080 (2,03)
0.045 (1,14)

0.006 (0,15)
0.004 (0,10)

0.280 (7,11) MAX

0.019 (0,48)
0.015 (0,38)

1   14

0.050 (1,27)

0.390 (9,91)
0.335 (8,51)

0.005 (0,13) MIN
4 Places

7   8

0.360 (9,14)
0.250 (6,35)

0.360 (9,14)
0.250 (6,35)

4040180–2/D 07/03

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. This package can be hermetically sealed with a ceramic lid using glass frit.
         D. Index point is provided on cap for terminal identification only.
         E. Falls within MIL STD 1835 GDFP1–F14 and JEDEC MO–092AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

0.020 (0,51) / 0.010 (0,25)

0.020 (0,51) / 0.010 (0,25)

0.080 (2,03) / 0.064 (1,63)

0.055 (1,40) / 0.045 (1,14)

0.045 (1,14) / 0.035 (0,89)

0.028 (0,71) / 0.022 (0,54)

0.045 (1,14) / 0.035 (0,89)

0.050 (1,27)

4040140 / D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. This package can be hermetically sealed with a metal lid.
        D. The terminals are gold plated.
        E. Falls within JEDEC MS-004

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

N (R−PDIP−T)**   **PLASTIC DUAL−IN−LINE PACKAGE**

16 PINS SHOWN

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS−001 VARIATION	AA	BB	AC	AD

0.260 (6,60) / 0.240 (6,10)

0.070 (1,78) / 0.045 (1,14) /D\

0.045 (1,14) / 0.030 (0,76) /D\

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53) / 0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

14/18 Pin Only
20 Pin vendor option /D\

0.325 (8,26) / 0.300 (7,62)

0.015 (0,38)
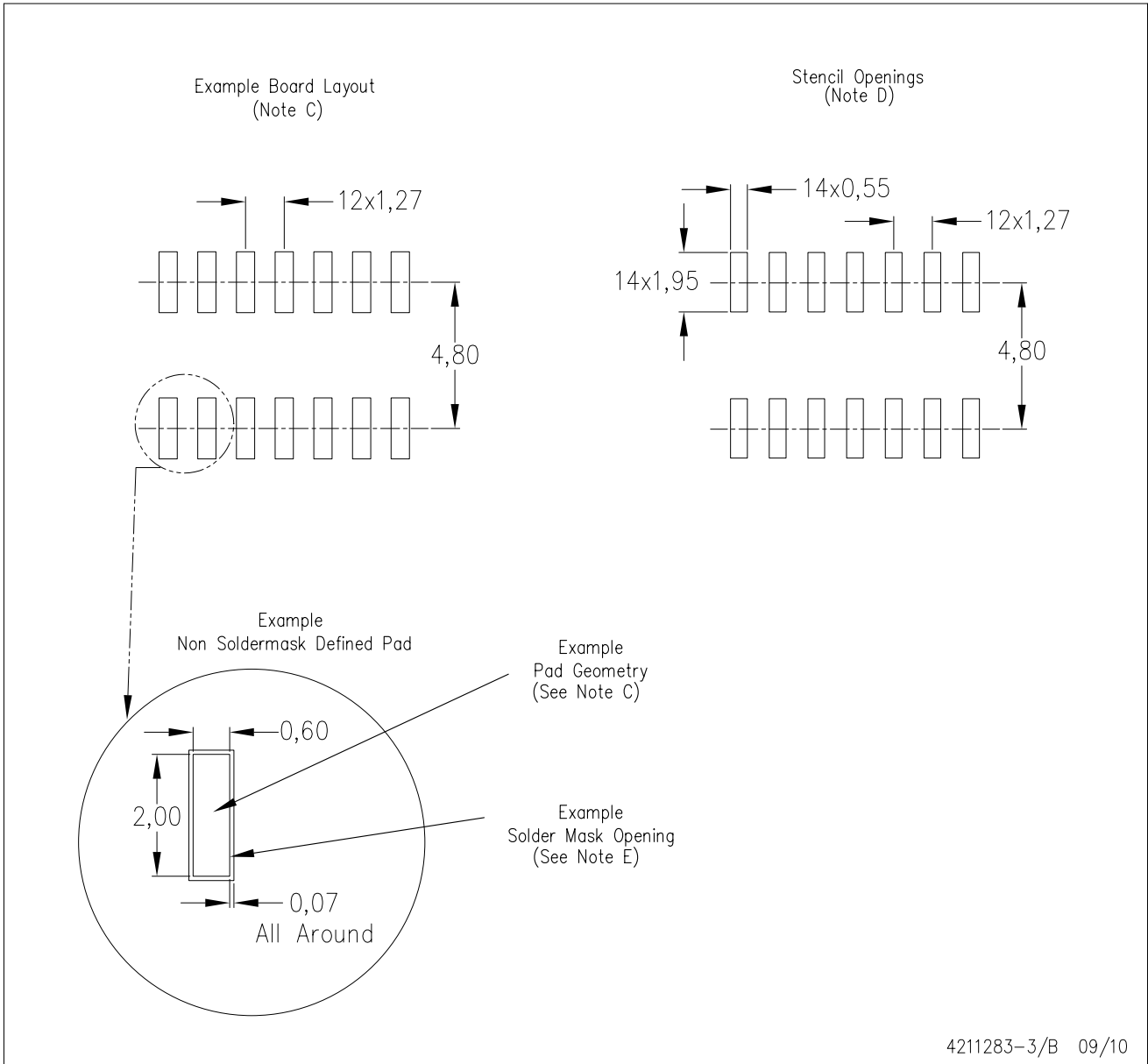
Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
       /C\ Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
      /D\ The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R−PDSO−G14)   PLASTIC SMALL−OUTLINE PACKAGE

0.344 (8,75)
0.337 (8,55)
△C

14   8

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80) △D

1   7

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ | 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°–8°

0.050 (1,27)
0.016 (0,40)

4040047−4/K 06/10

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
       △C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
             not exceed .006 (0,15) per end.
       △D Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
         E. Reference JEDEC MS−012 variation AB.

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

12x1,27

14x0,55

12x1,27

14x1,95

4,80

4,80

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

2,00

Example
Solder Mask Opening
(See Note E)

0,07

All Around

4211283−3/B 09/10

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Publication IPC−7351 is recommended for alternate designs.
         D.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E.   Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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NS (R-PDSO-G)**   PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

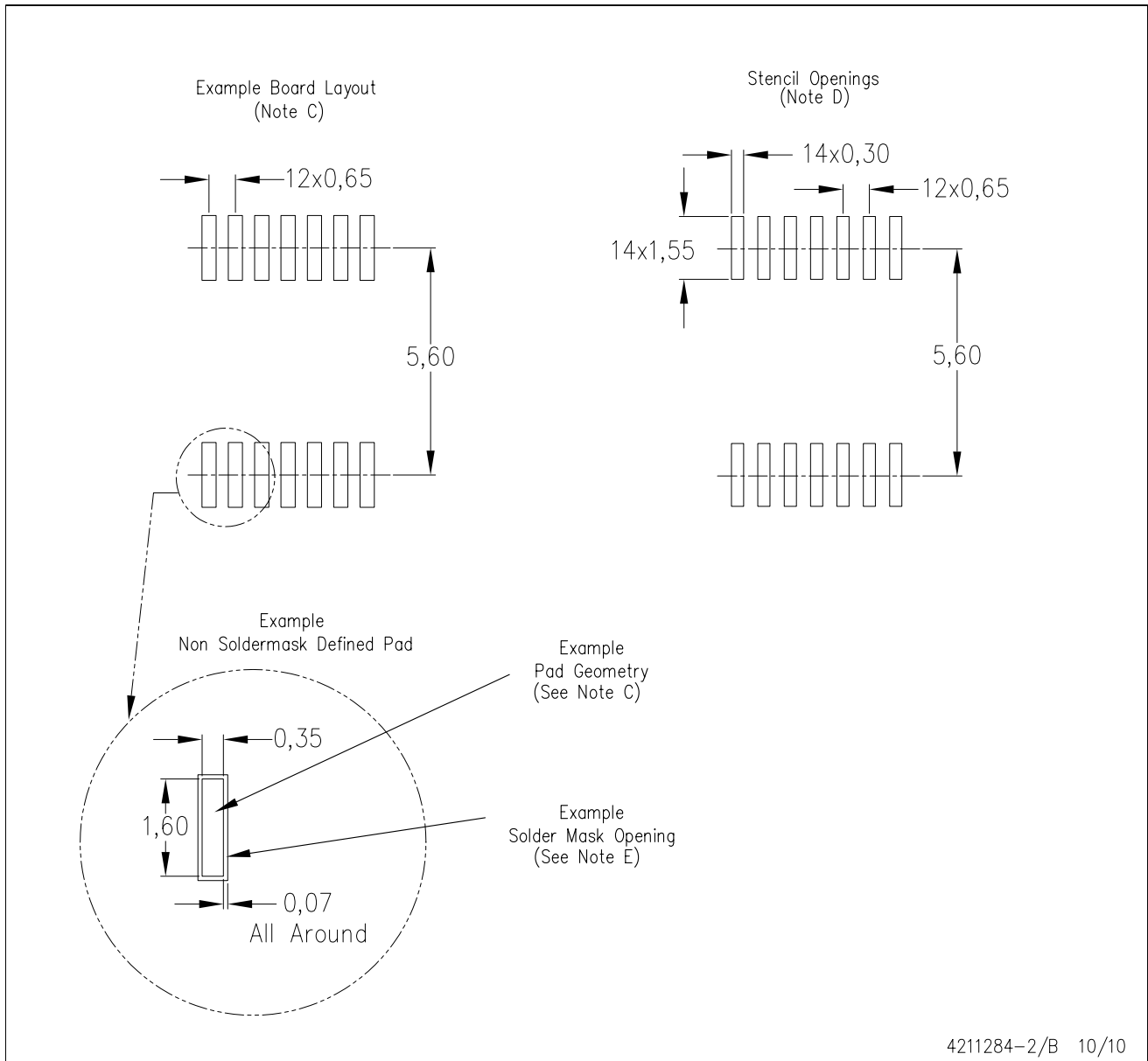| PINS ** DIM	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
          B.   This drawing is subject to change without notice.
          C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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MECHANICAL DATA

DB (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN

PINS ** DIM	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
         D. Falls within JEDEC MO-150

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PW (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN

PINS ** DIM	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

PW (R-PDSO-G14)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

12x0,65

5,60

Stencil Openings
(Note D)

14x0,30

12x0,65

14x1,55

5,60

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,35

1,60

0,07
All Around

Example
Solder Mask Opening
(See Note E)

4211284-2/B 10/10

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Publication IPC-7351 is recommended for alternate designs.
         D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
             contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
         E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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